

DOCKET NO. 99-102/1D

Express Mailing Label No. ET662218667US

2/FDS  
03/15/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Wilbur G. Catabay and  
Richard Schinella

Filed: Herewith

Serial Number: Unknown

Title: "Low k Dielectric Composite Layer for Integrated  
Circuit Structure Which Provides Void-Free Low k  
Dielectric Material Between Metal Lines While  
Mitigating Via Poisoning"

)  
)  
) Group Art Unit: 2813

)  
) Examiner: Lisa Kilday



INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.56

Honorable Commissioner of Patents  
and Trademarks  
Washington, D.C. 20231

Date: March 15, 2002

Sir:

Pursuant to 37 CFR 1.56, 1.97, and 1.98, Applicants submit the attached form PTO-1449 (modified). This application is a 37 C.F.R. 1.53(b) divisional application of Serial No. 09/426,056. Since all of the documents listed on the enclosed form PTO-1449 (modified) were previously cited to or by the USPTO in the prior application, under the provisions of 37 C.F.R. 1.98(d), copies of the listed documents are not enclosed.

Respectfully submitted,

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